

Etimol SW 25/FD RAN

Cat.-No. 5120

SMT-Stencil cleaning, fast drying within automatic equipment

Customer added value

Efficient removal of solder paste and SMT-adhesive from stencils grants repeatable and stable cleaning process which helps to achieve high-quality printing results. The waterbased formulation combines fast drying-effect, high flashpoint and work safety level and helps to eliminate flammable solvents from within the production area.

Please consider approvals of equipment manufacturer!

The waterbased, pH-neutral cleaning media efficiently removes leaded, lead-free, no clean solder pastes and SMT-adhesives from SMT-stencils within automatic cleaning equipment. ETIMOL SW 25/FD RAN shows excellent dissolving properties and fast drying that garant stable and hih quality cleaning results and shows excellent rinsability with itself and DI-water.

Special notes:

The cleaning media is used straight at room temperature and put within the cleaning tank of the automatic equipment.

Consider approvals of equipment manufacturer!

Consider compatibility of SMT-stencil adhesive!



Technical Data

Appearance/smell	colorless to slightly yellow, clear
Application	ready-to-use
Density at 20 °C	0,96 – 0,99 g/cm ³
pH-value	neutral
Boiling point/boiling range	93-95°C
System	waterbased
Flash point °C	82°C cc
Operations temperature	room temperature
Reliable cleaning results with	leades, lead-free, no-clean solder pastes SMT-adhesives
Durability	36 months
Storage conditions	ideal in original packaging at 10-25°C
Transportation	Non-DG
Packaging Units	5 l / 20 l plastic can

Application area

(Automatic) SMT stencil cleaning

Packaging units

Canister / 5/20 liters

Metering bottle / ml

Spray bottle / ml

Granulate / Size

Metering pen / ml

Injection / ml